

Product Change Notification - RMES-080KPK743

Date:

03 Mar 2020

Product Category:

Driver / Interface ICs

Affected CPNs:



Notification subject:

CCB 3914.002 Final Notice: Qualification of LPI as a new assembly site for selected Micrel products available in 16L SOIC (.300in) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the files found in the Affected CPNs section above to see all listed items.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of LPI as a new assembly site for selected Micrel products available in 16L SOIC (.300in) package.

Pre-Change:

Assembled at UNIB assembly site using CRM1076NS die attach material.

Post Change:

Assembled at LPI assembly site using 8340 die attached material.

Pre and Post Change Summary:

	Pre-Change	Post Change			
Accombly Site	Unisem (B) Batam, Indonesia	Lingsen Precision Industries,			
Assembly Site	(UNIB)	Taiwan. (LPI)			
Wire material	Au	Au			
Die attach material	CRM1076NS	8340			
Molding compound material	EME-G600	EME-G600			
Lead frame material	C194	C194			

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying LPI as a new assembly site. Due to unforeseen business conditions the UNIB location will be discontinued as an assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

April 03, 2020 (date code: 2014)



NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	N	November 2019			N	March 2020			April 2020						
Workweek	44	45	46	47	48	^	10	11	12	13	14	15	16	17	18
Initial PCN Issue Date		Χ													
Qual Report Availability							Χ								
Final PCN Issue Date							Χ								
Estimated Implementation Date											Χ				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

November 05, 2019: Issued initial notification.

March 03, 2020: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on April 03, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN RMES-08OKPK743 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)
MIC5891YWM
MIC5891YWM-TR
Date: Monday, March 02, 2020